



Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 SOCKETS



IC Socket Type: **LGA 3647**
 Connector System: **Board-to-Board**
 Number of Positions: **3647**
 Contact Mating Area Plating Material: **Gold**
 Contact Mating Area Plating Material Thickness: **[30 µin]**

[All LGA 3647 SOCKETS \(8\)](#)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Positions	3647
Grid Spacing	.9906 x .8585 mm [.039 x .0338 in]

Body Features

Frame Style	Square
Plating Material	Gold
Plating Thickness	30 µin

Contact Features

Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
Contact Mating Area Plating Material	Gold
	30 µin
Contact Current Rating (Max)	.5 A

Mechanical Attachment



Heat Sink Attachment	Without
PCB Mounting Style	Surface Mount Solder Ball
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	.86 mm, .99 mm [.034 in][.039 in]
Housing Material	High Temperature Thermoplastic
Housing Color	Black

Usage Conditions

Operating Temperature Range	-25 – 100 °C [-13 – 212 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Tray
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Other

Comment	Lead-Free Solderball
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # CAT-L59017-A76H
 LGA 3647 Socket Hardware



TE Part # CAT-D3304-SO1399
 DDR4 DIMM SOCKETS



TE Part # 2299806-1
 NRW NON-FABRIC CARRIER,
 SOCKET P0



TE Part # 2310927-1
 CARRIER, NARROW FABRIC, SOCKET
 P



TE Part # 2305234-1
 SOCKET P HARDWARE DUST COVER



TE Part # 5-2199154-4
 DDR4 DIMM 288 PIN TH TYPE



TE Part # 5-2199154-5
 DDR4 DIMM 288 PIN TH TYPE



TE Part # 2821722-2
 IFP/LEC CBL ASSY 1 PORT TYPE B
 STR INV



TE Part # 2821722-3
 IFP/LEC CBL ASSY 1 PORT TYPE B
 STR INV



TE Part # 2821722-4
 IFP/LEC CBL ASSY 1 PORT TYPE B
 STR INV

Customers Also Bought



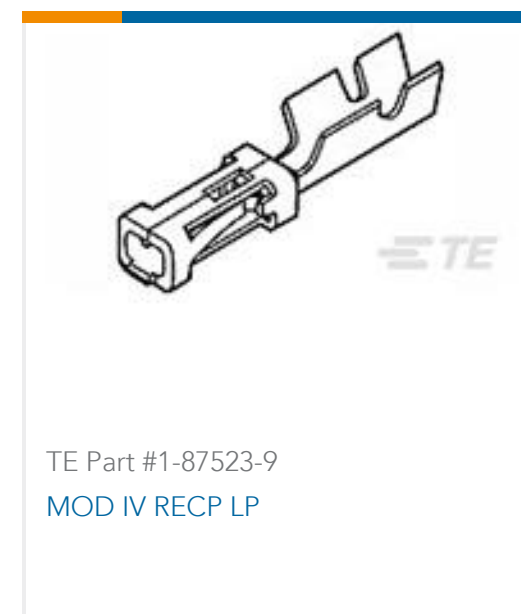
TE Part #1-1761987-8
ReceptacleConnAssm38PosTape/Re



TE Part #1-1734037-0
Champ 050 series 100pos,Au over PdNi



TE Part #1059402-1
4503 7941 00,OSP CABLE PLUG



TE Part #1-87523-9
MOD IV RECP LP



TE Part #1-2324271-1
RIGHT SEGMENT LGA4189-4
SOCKETP4 FOR ODM



TE Part #1-2324271-2
LEFT SEGMENT LGA4189-4 SOCKET-
P4 FOR ODM



TE Part #1-292251-2
AMP COMMON TERMINATION
HEADERS



TE Part #1410189-4
MULTIGIG RT T2 7RW H-LFT,ET2



TE Part #1410187-4
MULTIGIG RT T2 7RW DC DF CT



TE Part #EJ3089-000
100P160-15-1-B-WR5-03

Documents

Product Drawings

[LGA3647-0 SOCKET P0 KIT FOR ODM \(30U AU\)](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2-2822979-3_C.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2-2822979-3_C.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2-2822979-3_C.3d_stp.zip](#)

English

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Datasheets & Catalog Pages



[LGA 3647 Socket Product Flyer](#)

English

[Product Specifications](#)

[Application Specification](#)

English

[Product Environmental Compliance](#)

[MD_2-2822979-3_072420181410_dmtec](#)

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